1:2 CML Fanout Buffer with Selectable Clock Input

Features
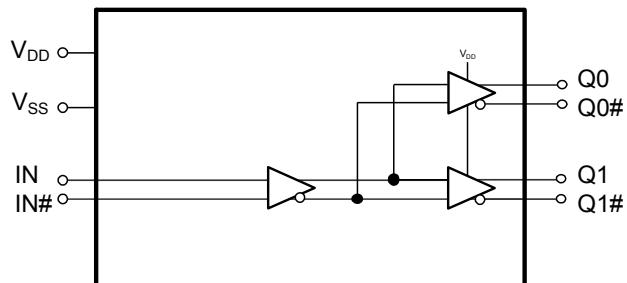
- One current mode logic (CML), High-speed current steering logic (HCSL), or low-voltage positive emitter-coupled logic (LVPECL) input pair distributed to two CML output pairs
- 20-ps maximum output-to-output skew
- 480-ps maximum propagation delay
- 0.15-ps maximum additive RMS phase jitter at 156.25 MHz (12-kHz to 20-MHz offset)
- Up to 1.5 GHz operation
- 8-pin thin shrunk small outline package (TSSOP) package
- 2.5-V or 3.3-V operating voltage [1]
- Commercial and industrial operating temperature range

Functional Description

The CY2DM1502 is an ultra-low noise, low-skew, low-propagation delay 1:2 CML, HCSL, or LVPECL to CML fanout buffer targeted to meet the requirements of high-speed clock distribution applications. The device has a fully differential internal architecture that is optimized to achieve low additive jitter and low skew at operating frequencies of up to 1.5 GHz.

For a complete list of related documentation, click here.

Logic Block Diagram

Note

1. Input AC-coupling capacitors are required for voltage-translation applications.

Contents

Pinouts

Figure 1. 8-pin TSSOP Package pinout
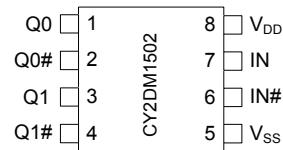
Pin Definitions

Pin No.	Pin Name	Pin Type	Description
1, 3	Q(0:1)	Output	CML output clocks
2, 4	Q(0:1)#	Output	CML complementary output clocks
5	V_{SS}	Power	Ground
6	IN#	Input	CML/HCSL/LVPECL complementary input clock
7	IN	Input	CML/HCSL//LVPECL input clock
8	V_{DD}	Power	Power supply

Absolute Maximum Ratings

Parameter	Description	Condition	Min	Max	Unit
V_{DD}	Supply voltage	Nonfunctional	−0.5	4.6	V
V_{IN}[2]	Input voltage, relative to V_{SS}	Nonfunctional	−0.5	lesser of 4.0 or V_{DD} + 0.4	V
V_{OUT}[2]	DC output or I/O voltage, relative to V_{SS}	Nonfunctional	−0.5	lesser of 4.0 or V_{DD} + 0.4	V
T_S	Storage temperature	Nonfunctional	−55	150	°C
ESD_{HBM}	Electrostatic discharge (ESD) protection (Human body model)	JEDEC STD 22-A114-B	2000	–	V
L_U	Latch up		Meets or exceeds JEDEC Spec JESD78B IC Latch-up Test		
UL–94	Flammability rating	At 1/8 in	V-0		
MSL	Moisture sensitivity level		3		

Operating Conditions

Parameter	Description	Condition	Min	Max	Unit
V_{DD}	Supply voltage	2.5-V supply	2.375	2.625	V
		3.3-V supply	3.135	3.465	V
T_A	Ambient operating temperature	Commercial	0	70	°C
		Industrial	−40	85	°C
t_{PU}	Power ramp time	Power-up time for V_{DD} to reach minimum specified voltage (power ramp must be monotonic).	0.05	500	ms

Note
2. The voltage on any I/O pin cannot exceed the power pin during power up. Power supply sequencing is NOT required.

DC Electrical Specifications

(V_{DD} = 3.3 V ± 5% or 2.5 V ± 5%; T_A = 0 °C to 70 °C (Commercial) or –40 °C to 85 °C (Industrial))

Parameter	Description	Condition	Min	Max	Unit
I_{DD}	Operating supply current	All CML outputs floating (internal I_{DD})	–	50	mA
V_{IH}	Input high voltage, CML/HCSL/LVPECL inputs IN and IN#		–	V_{DD} + 0.3	V
V_{IL}	Input low voltage, CML/HCSL/LVPECL inputs IN and IN#		–0.3	–	V
V_{ID}[3]	Input differential amplitude	See Figure 2 on page 7	0.4	1.0	V
V_{ICM}	Input common mode voltage	See Figure 2 on page 7	0.2	V_{DD} – 0.2	V
I_{IH}	Input high current, CML/HCSL/LVPECL inputs IN and IN#	Input = V_{DD}[4]	–	150	μA
I_{IL}	Input low current, CML/HCSL/LVPECL inputs IN and IN#	Input = V_{SS}[4]	–150	–	μA
V_{OH}	CML output high voltage	Terminated with 50 Ω to V_{DD}[5]	V_{DD} – 0.1	–	V
V_{OL}	CML output low voltage	Terminated with 50 Ω to V_{DD}[5]	V_{DD} – 0.7	V_{DD} – 0.3	V
C_{IN}	Input capacitance	Measured at 10 MHz; per pin	–	3	pF

Thermal Resistance

Parameter [6]	Description	Test Conditions	8-pin TSSOP	Unit
θ_{JA}	Thermal resistance (junction to ambient)	Test conditions follow standard test methods and procedures for measuring thermal impedance, in accordance with EIA/JESD51.	162	°C/W
θ_{JC}	Thermal resistance (junction to case)		29	°C/W

Notes
3. V_{ID} minimum of 400 mV is required to meet all output AC Electrical Specifications. The device is functional with V_{ID} minimum of greater than 200 mV.
4. Positive current flows into the input pin, negative current flows out of the input pin.
5. Refer to Figure 3 on page 7.
6. These parameters are guaranteed by design and are not tested.

AC Electrical Specifications

(V_{DD} = 3.3 V ± 5% or 2.5 V ± 5%; T_A = 0 °C to 70 °C (Commercial) or –40 °C to 85 °C (Industrial))

| Parameter	Description	Condition	Min	Typ	Max	Unit
F_{IN}	Input frequency		DC	–	1.5	GHz
F_{OUT}	Output frequency	F_{OUT} = F_{IN}	DC	–	1.5	GHz
V_{PP}	CML differential output voltage peak-to-peak, single-ended. Terminated with 50 Ω to V_{DD}[5]	Fout = DC to 150 MHz	250	–	700	mV
		Fout = >150 MHz to 1.5 GHz	250	–	600	mV
t_{PD}[7]	Propagation delay input pair to output pair	Input rise/fall time < 1.5 ns (20% to 80%)	–	–	480	ps
t_{ODC}[8]	Output duty cycle	50% duty cycle at input Frequency range up to 1 GHz	48	–	52	%
t_{SK1}[9]	Output-to-output skew	Any output to any output, with same load conditions at DUT	–	–	20	ps
$t_{SK1\,D}$[9]	Device-to-device output skew	Any output to any output between two or more devices. Devices must have the same input and have the same output load.	–	–	150	ps
PN_{ADD}	Additive RMS phase noise 156.25-MHz Input Rise/fall time < 150 ps (20% to 80%) V_{ID} > 400 mV	Offset = 1 kHz	–	–	−120	dBc/Hz
		Offset = 10 kHz	–	–	−130	dBc/Hz
		Offset = 100 kHz	–	–	−135	dBc/Hz
		Offset = 1 MHz	–	–	−145	dBc/Hz
		Offset = 10 MHz	–	–	−153	dBc/Hz
		Offset = 20 MHz	–	–	−155	dBc/Hz
t_{JIT}[10]	Additive RMS phase jitter (Random)	156.25 MHz, 12 kHz to 20 MHz offset; input rise/fall time < 150 ps (20% to 80%), V_{ID} > 400 mV	–	–	0.15	ps
t_R, t_F[11]	Output rise/fall time	50% duty cycle at input, 20% to 80% of full swing (V_{OL} to V_{OH}) Input rise/fall time < 1.5 ns (20% to 80%) Measured at 1 GHz	–	–	250	ps

Notes
7. Refer to Figure 4 on page 7.
8. Refer to Figure 5 on page 7.
9. Refer to Figure 6 on page 8.
10. Refer to Figure 7 on page 8.
11. Refer to Figure 8 on page 8.

**Figure 2. Input Differential and Common Mode Voltages**

IN

IN#

V_{ID}

V_A

$V_{ICM} = (V_A + V_B)/2$

V_B
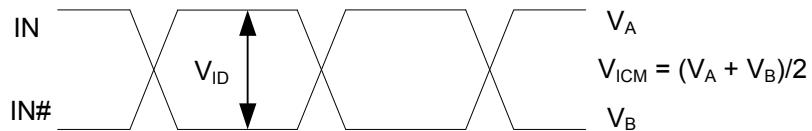
Figure 3. Output Differential Voltage

Q

Q#

V_{PP}

V_{OH}

V_{OL}
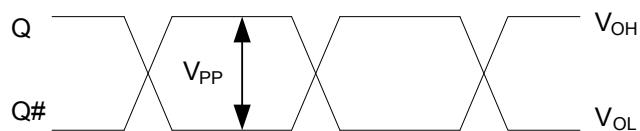
Figure 4. Input to Any Output Pair Propagation Delay

IN

IN#

Q_X

$Q_X\#$

t_{PD}
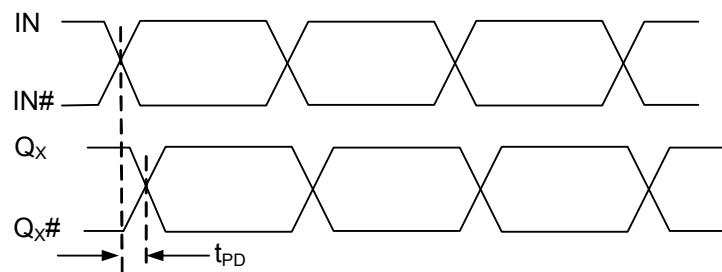
Figure 5. Output Duty Cycle

Q_X

$Q_X\#$

t_{PW}

t_{PERIOD}

$$t_{ODC} = \frac{t_{PW}}{t_{PERIOD}}$$
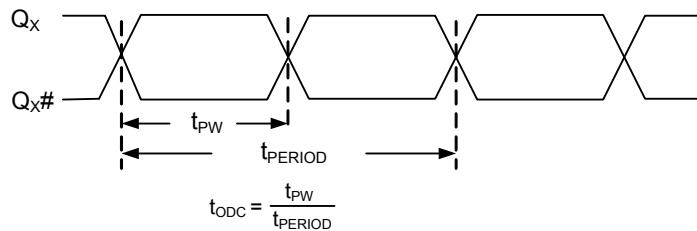
Figure 6. Output-to-Output and Device-to-Device Skew
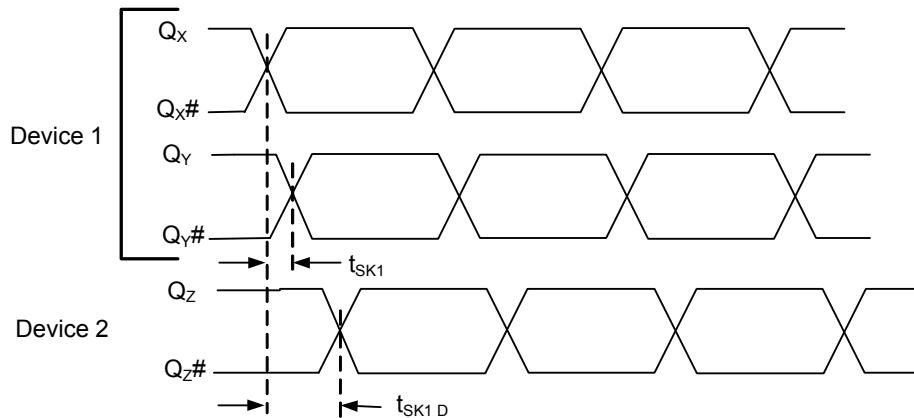
Figure 7. RMS Phase Jitter

$$\text{RMS Jitter} \propto \sqrt{\text{Area Under the Masked Phase Noise Plot}}$$
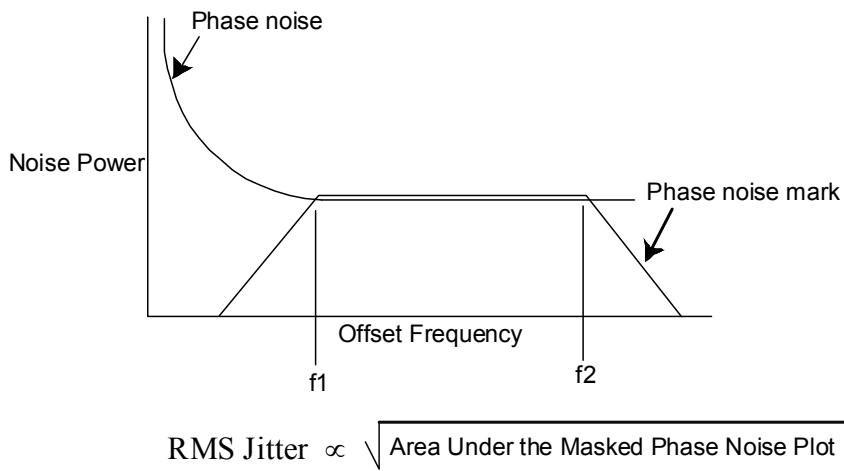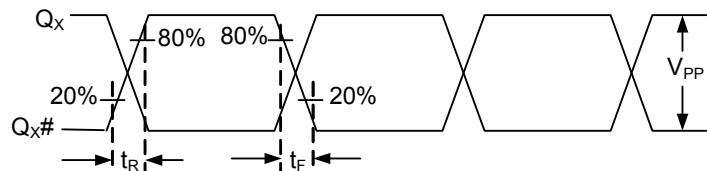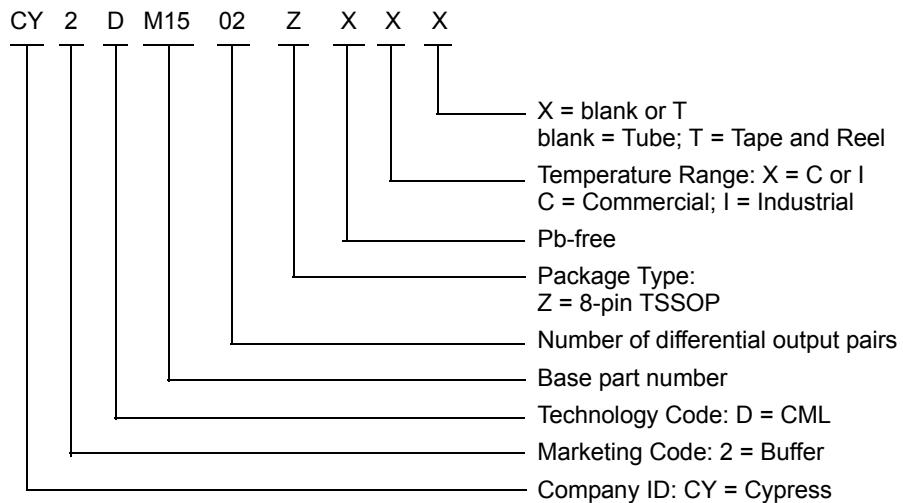
Figure 8. Output Rise/Fall Time

Ordering Information

Part Number	Type	Production Flow
Pb-free		
CY2DM1502ZXI	8-pin TSSOP	Industrial, –40 °C to 85 °C
CY2DM1502ZXIT	8-pin TSSOP tape and reel	Industrial, –40 °C to 85 °C

Ordering Code Definitions

CY 2 D M15 02 Z X X X

X = blank or T
blank = Tube; T = Tape and Reel

Temperature Range: X = C or I
C = Commercial; I = Industrial

Pb-free

Package Type:
Z = 8-pin TSSOP

Number of differential output pairs

Base part number

Technology Code: D = CML

Marketing Code: 2 = Buffer
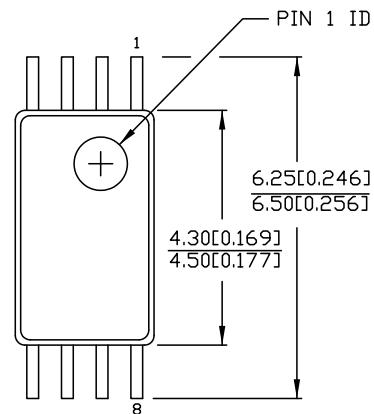
Company ID: CY = Cypress

Package Diagram

Figure 9. 8-pin TSSOP (4.40 MM Body) Z08.173/ZZ08.173 Package Outline, 51-85093

8 Lead TSSOP 4.40 MM BODY

PIN 1 ID

6.25[0.246]
6.50[0.256]

4.30[0.169]
4.50[0.177]
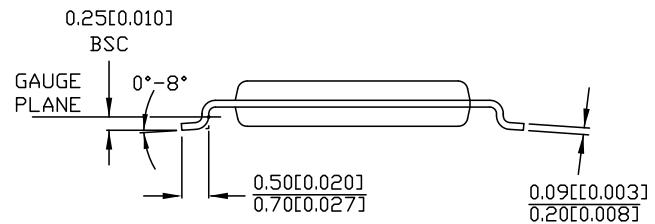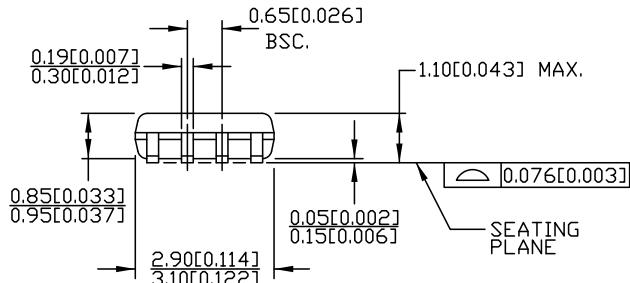
DIMENSIONS IN MM[INCHES] MIN.
                              MAX.

REFERENCE JEDEC MO-153

PART #	
Z08.173	STANDARD PKG.
ZZ08.173	LEAD FREE PKG.

0.65[0.026]
BSC.

0.19[0.007]
0.30[0.012]

1.10[0.043] MAX.

0.076[0.003]

0.85[0.033]
0.95[0.037]

0.05[0.002]
0.15[0.006]

SEATING PLANE

2.90[0.114]
3.10[0.122]

0.25[0.010]
BSC

GAUGE PLANE   0°-8°

0.50[0.020]
0.70[0.027]

0.09[0.003]
0.20[0.008]

51-85093 *E

Acronyms

Table 1. Acronyms Used in this Document

Acronym	Description
CML	current mode logic
ESD	electrostatic discharge
HBM	human body model
HCSL	high-speed current steering logic
JEDEC	joint electron devices engineering council
LVDS	low-voltage differential signal
LVCMOS	low-voltage complementary metal oxide semiconductor
LVPECL	low-voltage positive emitter-coupled logic
RMS	root mean square
TSSOP	thin shrunk small outline package

Document Conventions

Units of Measure

Table 2. Units of Measure

Symbol	Unit of Measure
°C	degree Celsius
dBc	decibels relative to the carrier
GHz	gigahertz
Hz	hertz
kΩ	kilohm
µA	microampere
µF	microfarad
µs	microsecond
mA	milliampere
ms	millisecond
mV	millivolt
MHz	megahertz
ns	nanosecond
Ω	ohm
pF	picofarad
ps	picosecond
V	volt
W	watt

Document History Page

Document Title: CY2DM1502, 1:2 CML Fanout Buffer with Selectable Clock Input Document Number: 001-56315				
Revision	**ECN**	**Orig. of Change**	**Submission Date**	**Description of Change**
**	2782891	CXQ	10/09/09	New Datasheet.
*A	2838916	CXQ	01/05/2010	Changed status from "ADVANCE" to "PRELIMINARY". Changed from 0.34 ps to 0.25 ps maximum additive jitter in "Features" on page 1 and in t_{JIT} in the AC Electrical Specs table on page 4. Added t_{PU} spec to the Operating Conditions table on page 2. Removed V_{OH} spec maximum of V_{DD} in the DC Electrical Specs table on page 3. Changed V_{OL} spec min from V_{DD} - 0.6V to V_{DD} - 0.7V; changed max from V_{DD} - 0.4V to V_{DD} - 0.3V in the DC Electrical Specs table on page 3. Removed V_{OD} spec of minimum 300 mV, maximum 450 mV in the DC Electrical Specs table on page 3. Added R_P spec in the DC Electrical Specs table on page 3. Min = 60 kΩ, Max = 140 kΩ. Added a measurement definition for C_{IN} in the DC Electrical Specs table on page 3. Added V_{PP} spec to the AC Electrical Specs table on page 4. V_{PP} max = 700 mV for DC - 150 MHz and max = 600 mV for 150 MHz to 1.5 GHz. V_{PP} min = 250 mV over the entire range. Changed letter case and some names of all the timing parameters in the AC Electrical Specs table on page 4 to be consistent with EROS. Lowered all additive phase noise mask specs by 3 dB in in the AC Electrical Specs table on page 4. Added condition to t_R and t_F specs in the AC Electrical specs table on page 4 that input rise/fall time must be less than 1.5 ns (20% to 80%). Changed letter case and some names of all the timing parameters in Figures 3, 4, 5, 6 and 8, to be consistent with EROS.
*B	3011766	CXQ	08/20/2010	Changed from 0.25 ps to 0.11 ps maximum additive jitter in "Features" on page 1 and in t_{JIT} in the AC Electrical Specs table. Added note 3 to describe I_{IH} and I_{IL} specs. Removed reference to data distribution from "Functional Description". Changed R_P for diff inputs from 100 kΩ to 150 kΩ in the Logic Block Diagram and from 60 kΩ min / 140 kΩ max to 90 kΩ min / 210 kΩ max in the DC Electrical Specs table. Added max V_{ID} of 1.0V in DC Electrical Specs table. Updated phase noise specs for 1 k/10 k/100 k/1 M/10 M/20 MHz offset to -120/-130/-135/-150/-150/-150dBc/Hz, respectively, in the AC Electrical Specs table. Added "Frequency range up to 1 GHz" condition to t_{ODC} spec. Updated package diagram. Added Acronyms and Ordering Code Definition.
*C	3017258	CXQ	08/27/2010	Corrected Output Rise/Fall time diagram.
*D	3100234	CXQ	11/18/2010	Updated Phase jitter to 0.15ps max from 0.11ps max. Changed V_{IN} and V_{OUT} specs from 4.0V to "lesser of 4.0 or V_{DD} + 0.4" Removed 200mA min LU spec, replaced with "Meets or exceeds JEDEC Spec JESD78B IC Latchup Test" Removed R_P spec for differential input clock pins IN_X and IN_X#. Changed C_{IN} condition to "Measured at 10 MHz". Changed PN_{ADD} specs for 1MHz, 10MHz, and 20MHz offsets. Added condition "Measured at 1 GHz" to t_R, t_F specs.
*E	3137726	CXQ	01/13/2011	Removed "Preliminary" status heading. Removed resistors from IN/IN# in Logic Block Diagram.
*F	3090938	CXQ	02/25/2011	Post to external web.

Document History Page (continued)

Document Title: CY2DM1502, 1:2 CML Fanout Buffer with Selectable Clock Input Document Number: 001-56315				
Revision	**ECN**	**Orig. of Change**	**Submission Date**	**Description of Change**
*G	3410372	PURU	10/18/2011	Adding HCSL to Features, Functional Description, Pin Definitions, and DC Electrical Specifications sections. The min value of V_{ICM} is changed from 0.5 to 0.2 in DC Electrical Specifications.
*H	3878396	PURU	01/21/2013	Updated to new template.
*I	4587249	PURU	12/04/2014	Updated Functional Description: Added "For a complete list of related documentation, click here." at the end. Updated Ordering Information: Removed the prune part numbers CY2DM1502ZXC and CY2DM1502ZXCT. Updated Package Diagram: spec 51-85093 – Changed revision from *D to *E.
*J	5272915	PSR	05/16/2016	Added Thermal Resistance. Updated to new template.
*K	5966682	AESATMP8	11/14/2017	Updated logo and Copyright.

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